

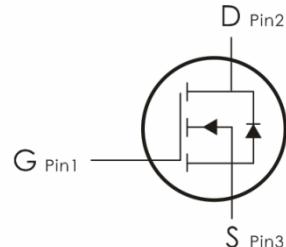
## Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent  $R_{DS(on)}$  with low gate charge.

It can be used in a wide variety of applications.

## Features:

- 1)  $V_{DS}=100V, I_D=170A, R_{DS(ON)}<3m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>1</sup>	170	A
	Pulsed Drain Current <sup>2</sup>	510	
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	540	mJ
$P_D$	Power Dissipation <sup>3</sup>	340	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55-+150	°C

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\Theta_{JC}}$	Thermal Resistance,Junction to Case	0.37	°C/W
$R_{\Theta_{JA}}$	Thermal Resistance,Junction to Ambient <sup>5</sup>	62	

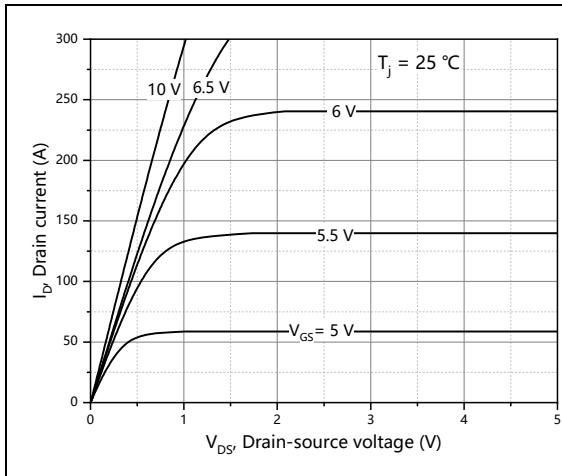
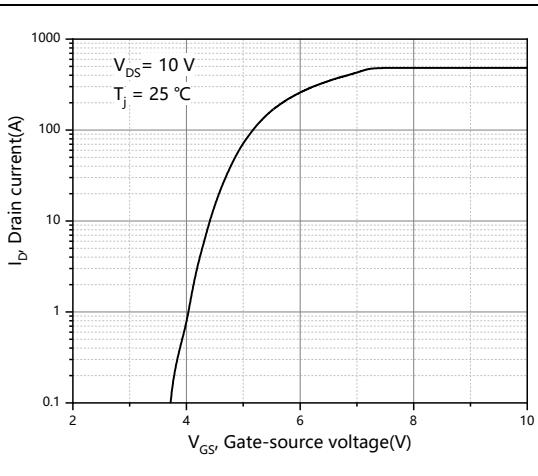
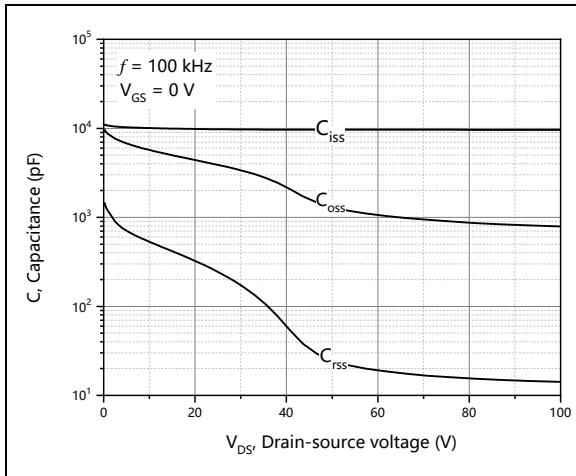
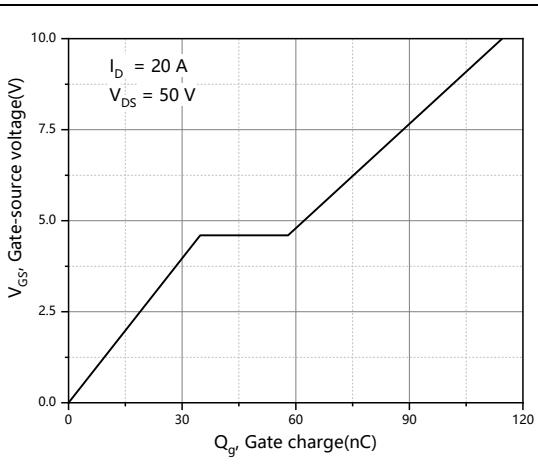
**Electrical Characteristics:** ( $T_c=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>Off Characteristics</b>						
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu\text{A}$	100		---	V
<b>I<sub>DSS</sub></b>	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=100V$	---	---	1	$\mu\text{A}$
<b>I<sub>GSS</sub></b>	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
<b>V<sub>GS(th)</sub></b>	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu\text{A}$	2		4	V
<b>R<sub>DS(on)</sub></b>	Drain-Source On Resistance	$V_{GS}=10V, I_D=30A$	---	2.8	3	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
<b>C<sub>iss</sub></b>	Input Capacitance <sup>4</sup>	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	---	9644.2	---	pF
<b>C<sub>oss</sub></b>	Output Capacitance <sup>4</sup>		---	1300.4	---	
<b>C<sub>rss</sub></b>	Reverse Transfer Capacitance <sup>4</sup>		---	24.6	---	
<b>Switching Characteristics</b>						
<b>t<sub>d(on)</sub></b>	Turn-On Delay Time	$V_{DD}=50V, I_D=20A,$ $R_{GEN}=2 \Omega, V_{GS}=10V$	---	43.7		ns
<b>t<sub>r</sub></b>	Rise Time		---	19.7		ns
<b>t<sub>d(off)</sub></b>	Turn-Off Delay Time		---	102.3		ns
<b>t<sub>f</sub></b>	Fall Time		---	22.5		ns
<b>Q<sub>g</sub></b>	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V,$ $I_D=20A$	---	114.5		nC
<b>Q<sub>gs</sub></b>	Gate-Source Charge		---	34.8	---	nC
<b>Q<sub>gd</sub></b>	Gate-Drain "Miller" Charge		---	23.2	---	nC
<b>V<sub>plateau</sub></b>	Gate plateau voltage			4.6		V
<b>Drain-Source Diode Characteristics</b>						
<b>V<sub>SD</sub></b>	Source-Drain Diode Forward Voltage	$V_{GS}=0V, I_S=20A$	---	---	1.3	V
<b>I<sub>s</sub></b>	Diode Forward Current	$V_{GS} < V_{th}$	---	---	170	A
<b>I<sub>SP</sub></b>	Pulsed source current				510	A

<b>Trr</b>	Reverse Recovery Time	$I_S=20\text{ A}$ , $di/dt=100\text{ A}/\mu\text{s}$	---	105	---	NS
<b>Qrr</b>	Reverse Recovery Charge		---	414.7	---	NC
<b>I<sub>rrm</sub></b>	Peak reverse recovery current			6.6		A

**Notes:**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4)  $V_{DD}=50\text{ V}$ ,  $R_G=50\Omega$ ,  $L=0.3\text{ mH}$ , starting  $T_j=25^\circ\text{C}$ .
- 5) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .

**Typical Characteristics:** ( $T_c=25^\circ\text{C}$  unless otherwise noted)

**Figure 1, Typ. output characteristics**

**Figure 2, Typ. transfer characteristics**

**Figure 3, Typ. capacitances**

**Figure 4, Typ. gate charge**

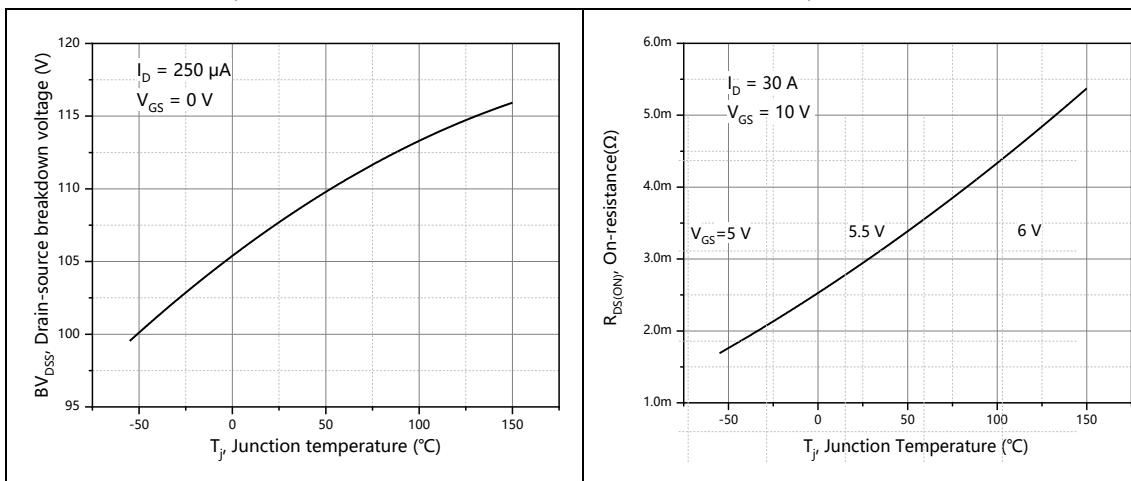


Figure 5, Drain-source breakdown voltage

Figure 6, Drain-source on-state resistance

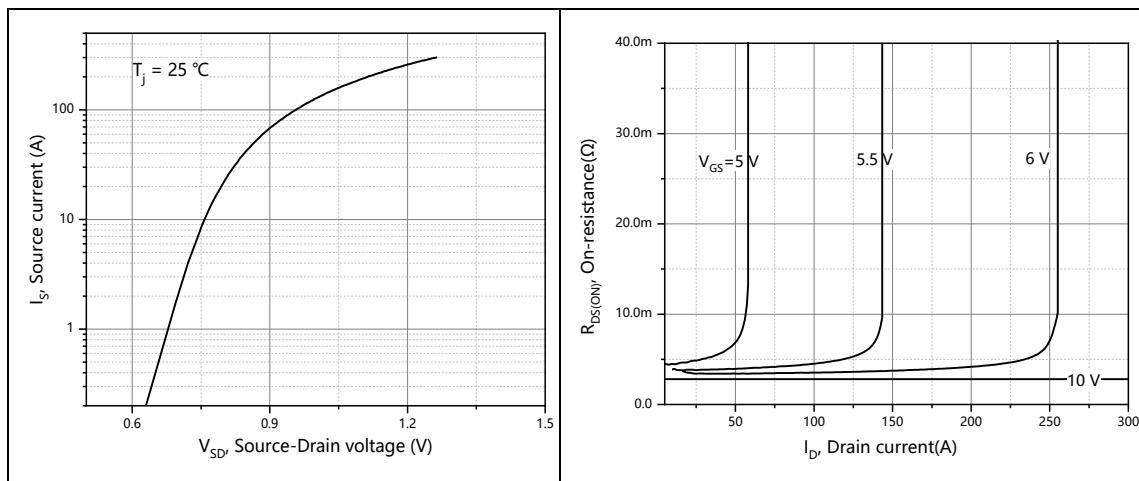


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance

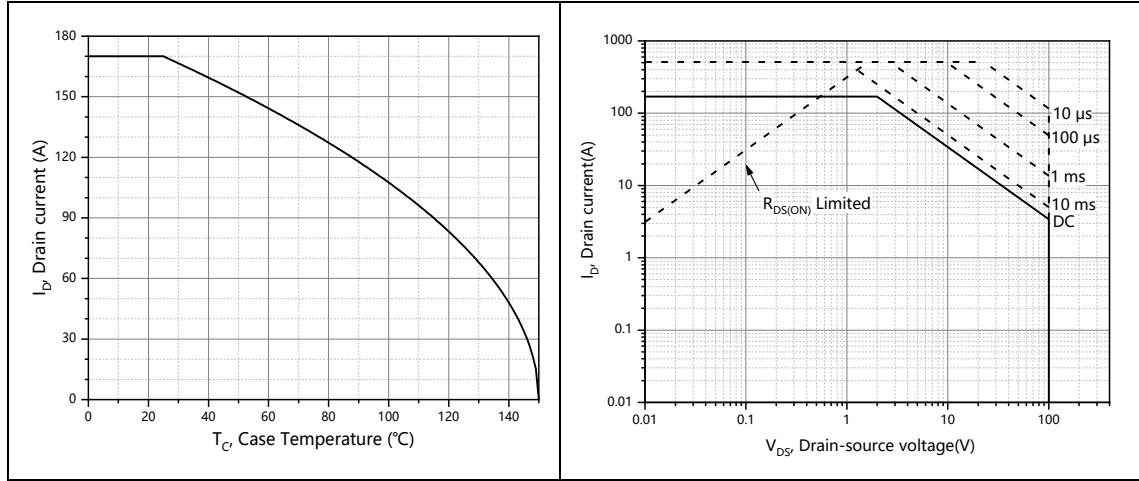
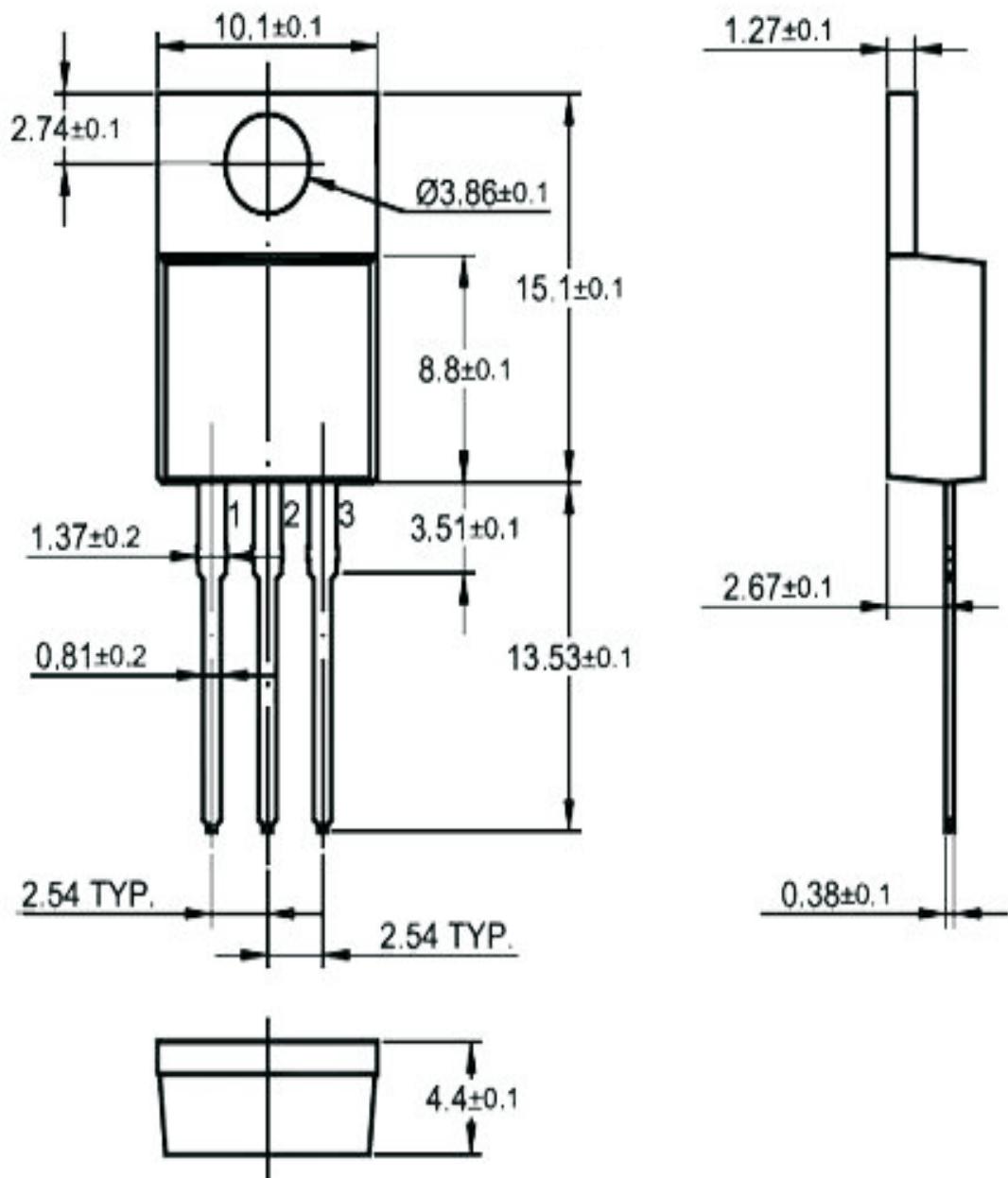


Figure 9, Drain current

Figure 10, Safe operation area  $T_c=25\text{ }^{\circ}\text{C}$



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